

formed on the substrate and the gate layer, wherein the first insulator layer has a flat part and two vertical walls, the flat part being formed between the two vertical walls; a semiconductor layer formed on the first insulator layer, wherein  
5 the semiconductor layer has two channels formed on the two vertical walls, and a first doped area and a second doped area formed to connect with the ends of the two channels respectively, and an intrinsic area formed on the flat part between the first doped area and the second doped area; a second insulator layer  
10 formed and covering over the two channels; and a metal layer formed on the semiconductor layer separately.

The process of the present invention successfully decreases the fabrication cost by simplifying the conventional CMOS process. Furthermore, leakage current is also reduced in  
15 the above CMOS with a dual gate and offset structure. Moreover, the double vertical channel (DVC) structure of the above CMOS side steps the photolithography limitation because the deep-submicrometer channel length is determined by the thickness of gate, thereby decreasing the channel length substantially.

#### BRIEF DESCRIPTION OF THE DRAWINGS

The present invention can be more fully understood by reading the subsequent detailed description in conjunction with the examples and references made to the accompanying drawings,  
25 wherein:

(6a-6b)

B Figs. 1 to 6 are sectional views showing an embodiment of the CMOS process for double vertical channel thin film transistor according to the present invention.

#### DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENT

Embodiment 1

As shown in Fig. 1, a gate layer 20 is deposited on a substrate 10. The gate layer 20, is preferably deposited by APCVD, LPCVD, PECVD, sputtering system, or e-gun evaporation, and is preferably composed of doped polysilicon, doped amorphous silicon, transition metals, metal silicide, polycide of metal, aluminum, aluminum alloy, or copper.

As shown in Fig. 2, a gate insulator layer 30 is deposited on the substrate 10 and the gate layer 20. The gate insulator layer 30, is preferably deposited by APCVD, LPCVD, PECVD, sputtering system, or e-gun evaporation, and is preferably composed of nitride, oxide, or oxynitride.

As shown in Fig. 3, a semiconductor layer 40 is deposited on the gate insulator layer 30. The semiconductor layer 40, is preferably deposited by APCVD, LPCVD, PECVD, sputtering system, or e-gun evaporation, and is preferably composed of single crystal silicon, polysilicon, amorphous silicon, or silicon-~~germanium~~. *germanium*

As shown in Fig. 4, a mask 50 is deposited on the surface of I area of the semiconductor layer 40, and  $N^+$  ions are implanted to the other surface of the semiconductor layer 40 to define a  $N^+$  doped area 42 and a channel 46. Then, the mask 50 is removed. Furthermore, as shown in Fig. 5, a mask 52 is deposited on the surface of II area of the semiconductor layer 40, and  $P^+$  ions are implanted to the other surface of the semiconductor layer 40 to define a  $P^+$  doped area 44 and a channel 46 of the II area and an intrinsic area 54 of the III area. Then, the mask 52 is removed. In this case, the two channels 46 are called double vertical channel (DVC). The DVC structure side steps the conventional photolithography limitation because the